

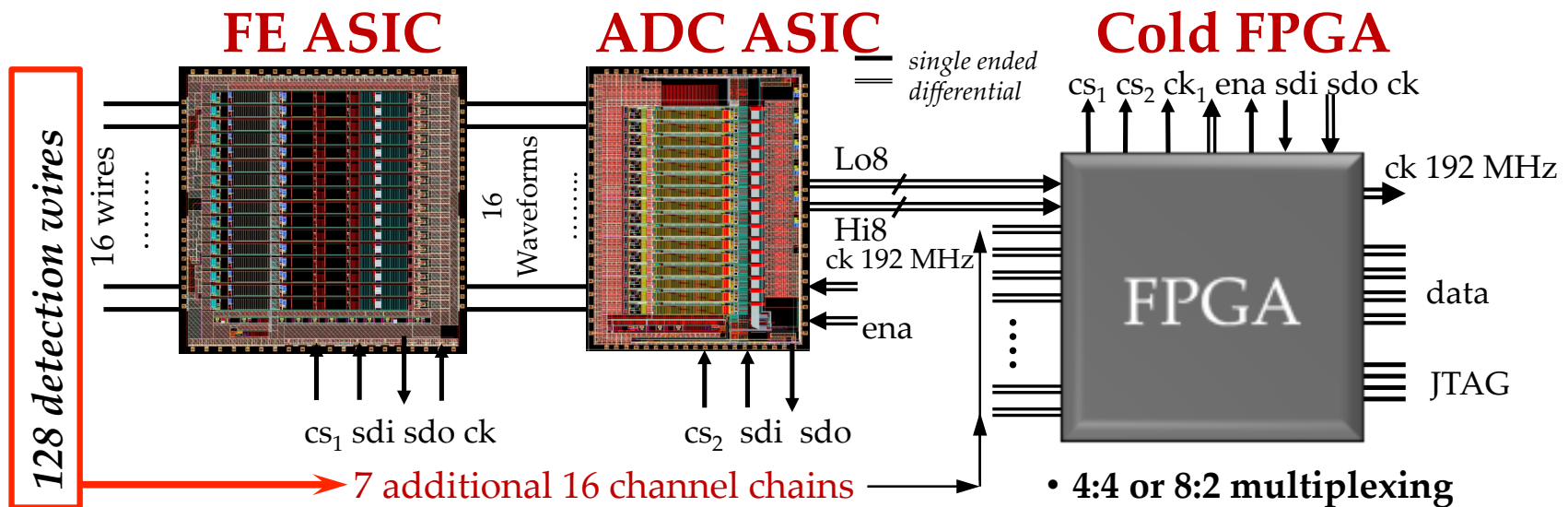
Readout Electronics for LArTPC

NOVEMBER 6TH, 2014

Outline

- TPC Front End
- Light Collection Front End
- Back End
- Signal Feed-through

TPC Front End Cold Electronics

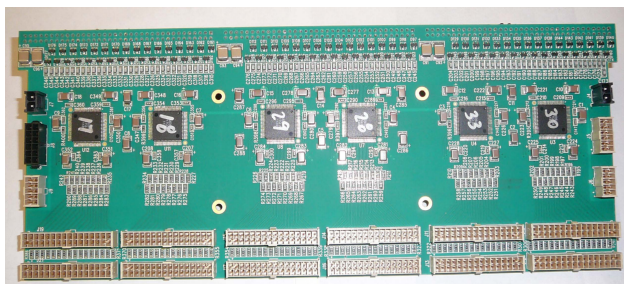


- low-noise analog amplification
- programmable gain, shaping, coupling, ...
- charge calibration over all chips, channels and temperatures to 1%

- ADC 12-bit 2MS/s sampling rate
- built-in FIFO
- serialized outputs
- **2 x 8:1 multiplexing**

- **4:4 or 8:2 multiplexing**
(total 32:4 or 64:2)
- timestamp
- compression
- zero suppression
- neighbor triggering
- **support non-reduction transparent mode**
- **max output data rate 960Mbit/s or 1.92Gbit/s with overhead of 8B/10B**

FE ASIC



MicroBooNE cold mother board with 12 analog FE ASICs (192 channels)

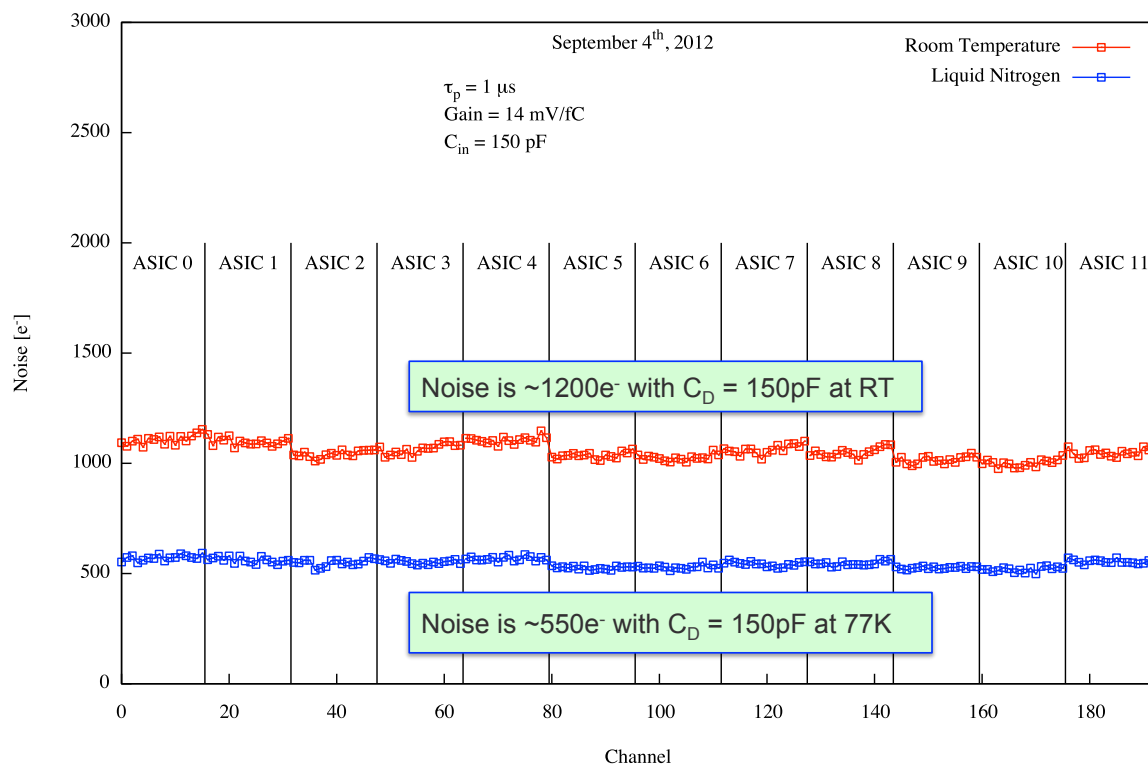


50 cold mother boards (8,256 channels) are installed on MicroBooNE TPC

11/06/2014

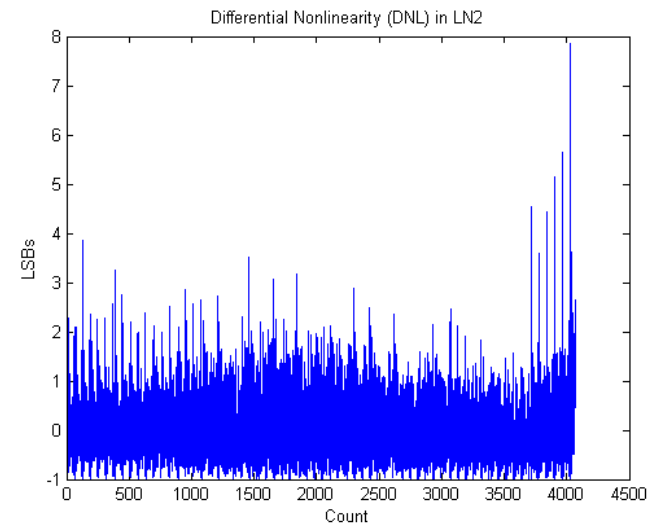
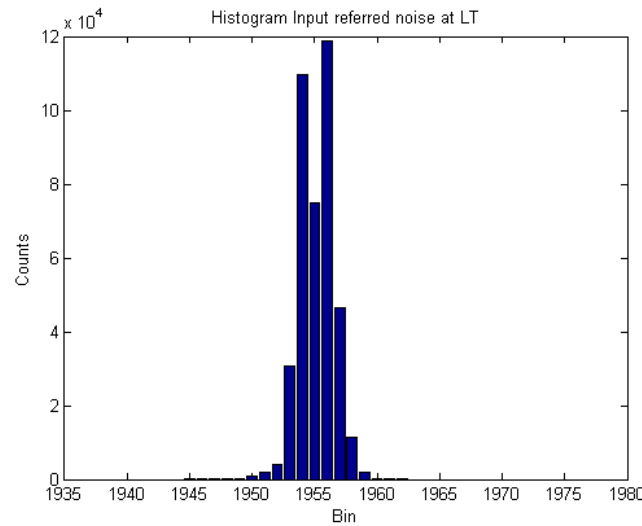
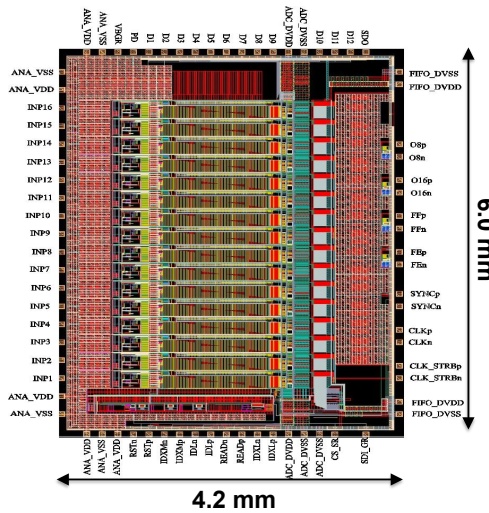
ArgonCube Discussion

Noise vs. Temperature: 12 ASICs (192 channels)



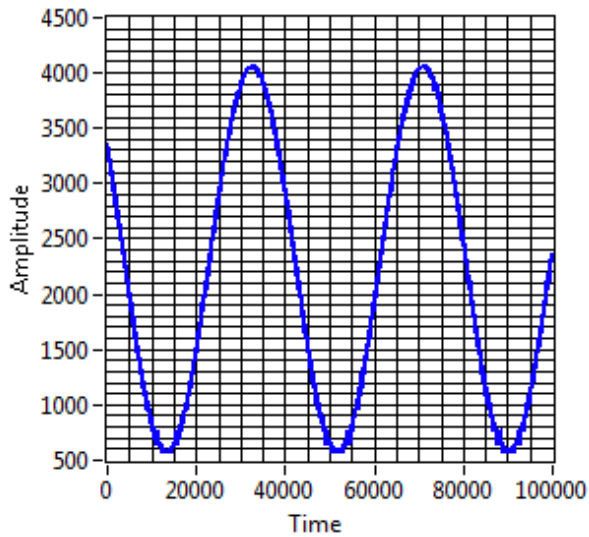
- 16-channel FE ASIC with programmable gain and peaking time
- Low power consumption $\sim 6 \text{ mW/ch}$ without buffer
- FE ASIC is ready to use for TPC readout
 - *Plan to revise the design to include build-in pulse generator*

ADC ASIC



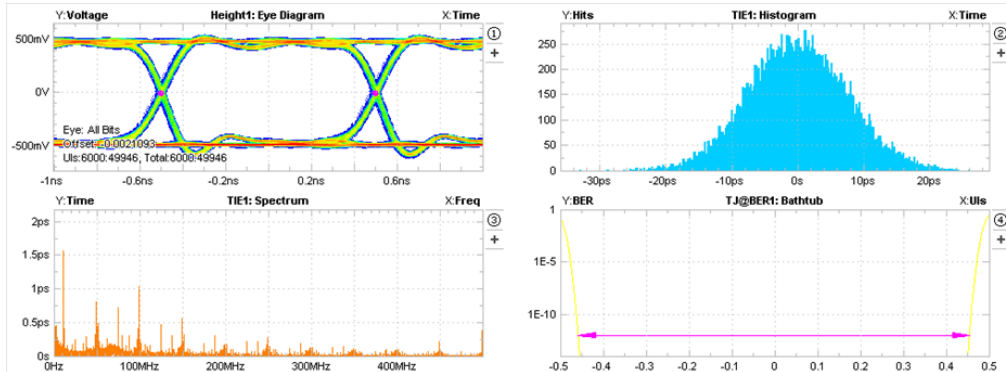
Waveform Graph

Plot 0

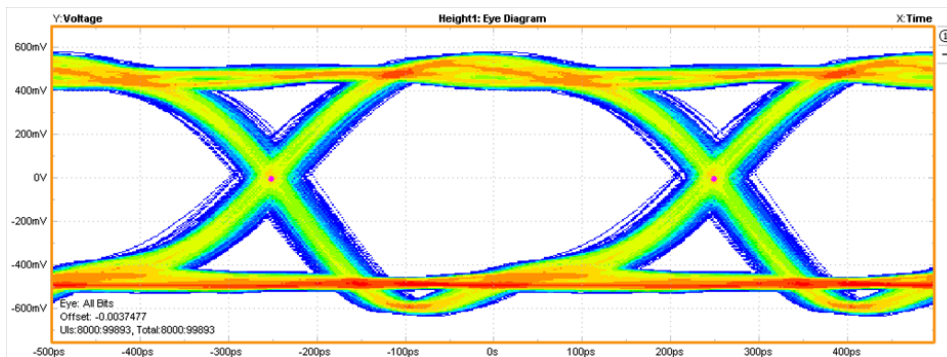


- 16-channel ADC with built-in FIFO
- Low power consumption < 5 mW/ch
 - ADC ~ 4.8 mW/ch and FIFO ~ 1 mW for 16 channels
- Very good results have been obtained from prototype design
 - Effective resolution w.r.t. input referred noise is ~ 11.6 bits at both 300 K and 77 K
 - Differential non-linearity (DNL) is less than 4 LSBs for 99% ADC bins at both 300 K and 77 K
- ADC ASIC is ready to use for TPC readout
 - *Plan to revise the design to include default power on configuration*

Cold FPGA



Measurement plots @ 1 Gb/s

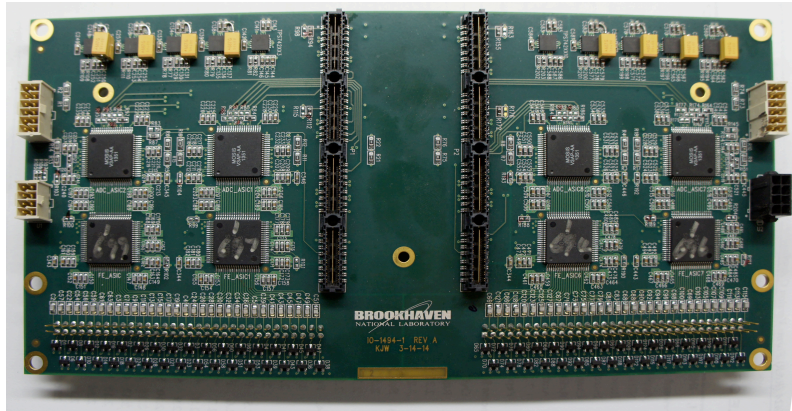


Eye diagram @ 2 Gb/s

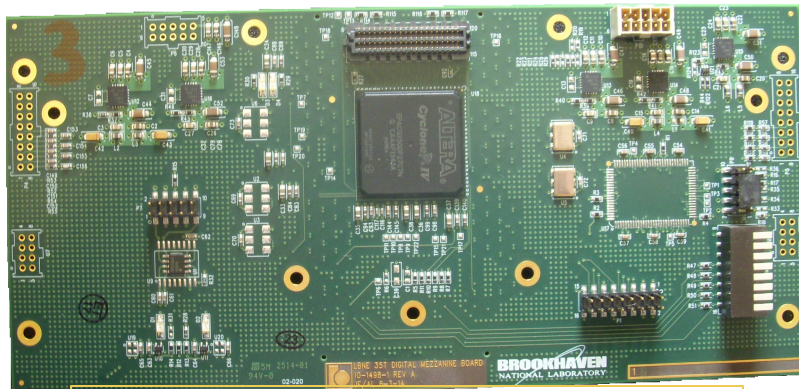
Test of Cyclone IV GX Transceiver Starter Board in LN₂

- *Transceiver works well at both 1Gbit/s and 2Gbit/s*
- Height
 - 839mV @ 1Gbit/s
 - 823mV @ 2Gbit/s
- Eye Width
 - 914ps @ 1Gbit/s
 - 357ps @ 2Gbit/s
- *On board SRAM works with BIST*
 - 18-Mb SRAM from ISSI IS61VPS102418A-250TQL
 - Cyclone IV GX is running with Nios II processor and utilization of ~80% fabric resources

Front End Mother Board for 35 Ton



Analog Mother Board



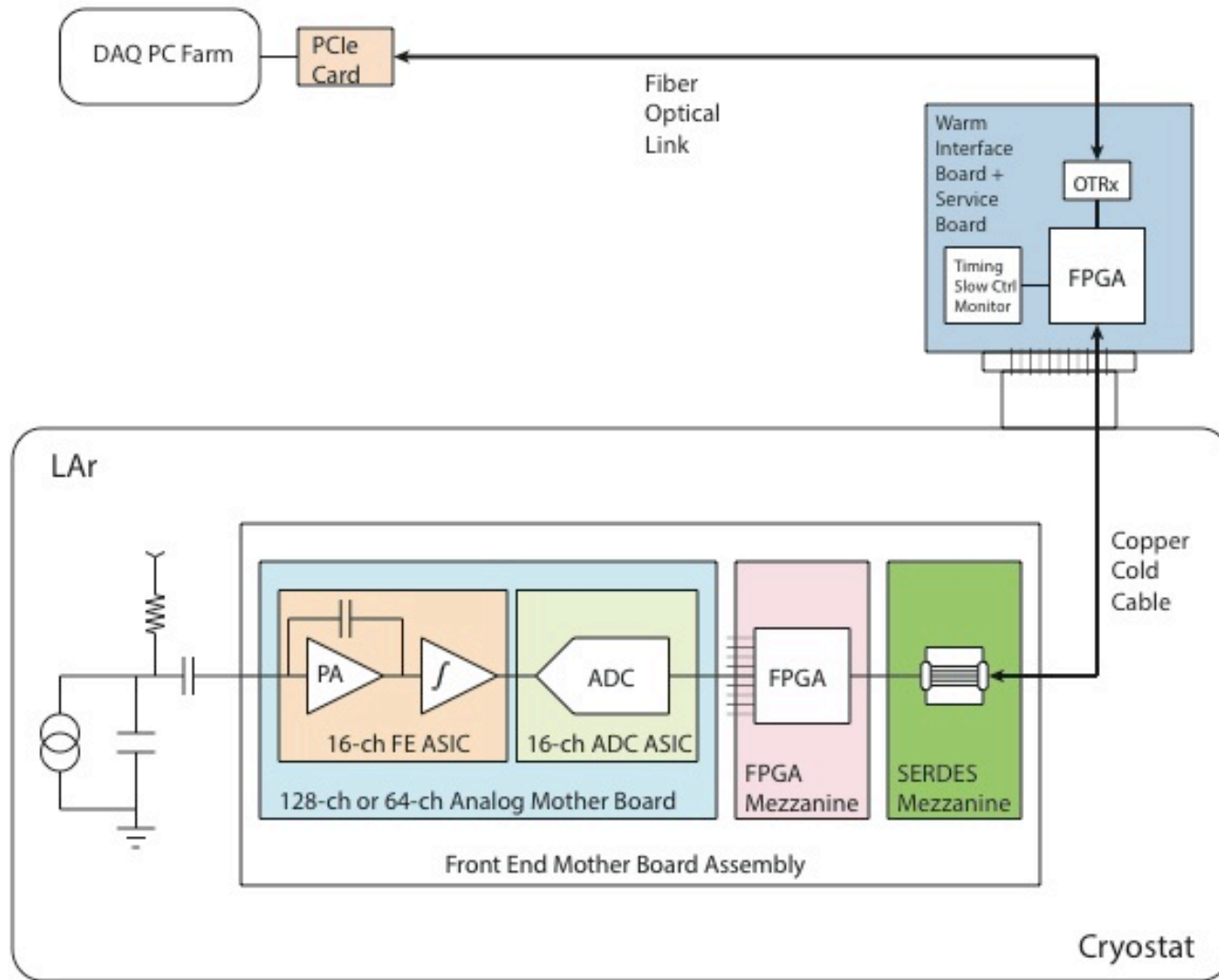
FPGA Mezzanine

- 128 channels
- 8 Analog FE ASICs
- 8 ADC ASICs
- Altera Cyclone IV GX FPGA
- Voltage regulator
 - TI TPS74201: 1.5A, adjustable output (0.8V to 3.6V)
- *Front End Mother Board could be revised for TPC anode design*

Light Collection Front End

- BNL is working on the R&D of low noise cryogenic front end for SiPM readout of nEXO experiment
 - 16 channel front end ASIC, ~500 chips, 40 W
 - Preamplifier and shaper
 - Peaking time: 250 ns – 1 us
 - Peak/hold and timing flag
 - Timing at peak of shaped pulse (~10 ns res.)
 - Timing flag width 10 ns – 50 ns
 - Peak/hold autoreset 1 – 10 us
 - Coincidence logic on flag
 - Coincidence window 50 – 200 ns
 - Coincidence number 1 – 8
 - Adjustable output flag width
 - Channel mask
 - Digitization, control logics and DAQ is in the warm
- Could be applicable to LArTPC light collection readout

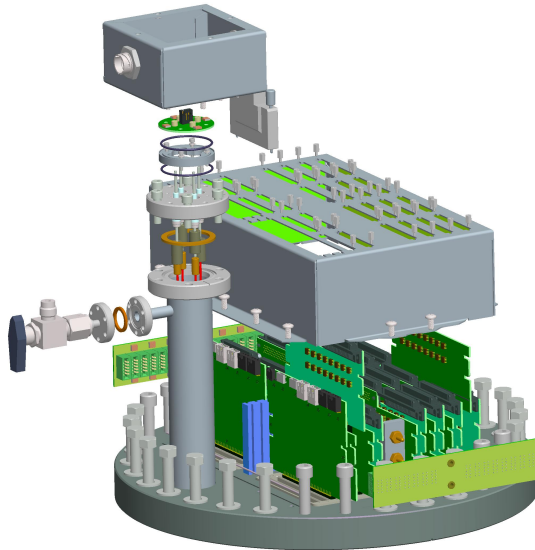
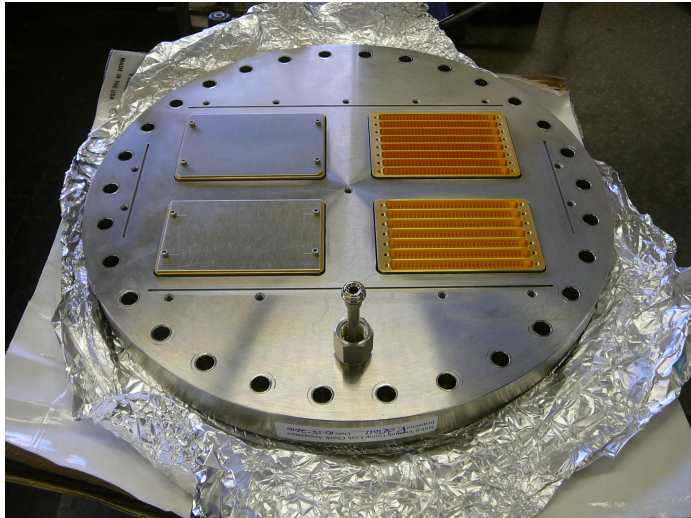
Back End



Back End

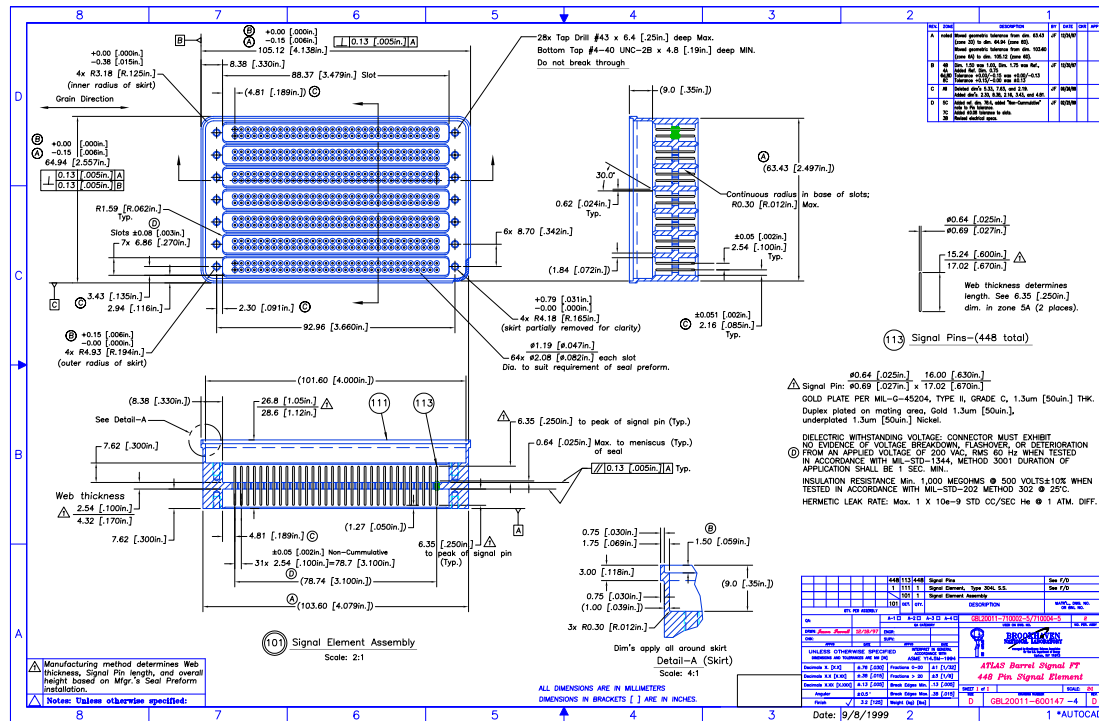
- Warm interface electronics
 - Warm interface board is to receive serial data from TPC front end and send to DAQ system
 - Service board is to provide power distribution, timing, slow control and monitoring
 - Both will be developed for LAr1-ND
- A PCIe Gen3 x8 card is being developed for ATLAS Phase-I upgrade
 - Virtex-7 FPGA is the core processor
 - 48-ch optical transceivers running at 10 Gb/s per channel
 - DDR3 on board memory for event buffer
 - Receiving data from, and distributing timing, trigger and control information to the front end

Signal Feed-through



- ATLAS LAr Calorimeter Feed-through
 - Pin carrier welded on flange: 100% hermetic
 - 2x8 + 2x7 rows pin carrier: high signal density 1920-pin/FT
 - Designed for both warm and cold flanges
- MicroBooNE adopted same pin carrier design for 11 warm signal feed-throughs
- Technology exist: no development required
- Pin carrier has been tested to be capable of running at 2 Gb/s

Signal Feed-through



- Original manufacture Glasseal, part of AMETEK HCC Industries Inc., has been contacted
 - Quote is available, ~\$5k per pin carrier for small quantity of order